

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please cancel claims 1-13 and add new claims 14-33 in accordance with the following:

1. (CANCELLED)
2. (CANCELLED)
3. (CANCELLED)
4. (CANCELLED)
5. (CANCELLED)
6. (CANCELLED)
7. (CANCELLED)
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9. (CANCELLED)
10. (CANCELLED)
11. (CANCELLED)
12. (CANCELLED)
13. (CANCELLED)

14. (New) An electrical device comprising:
a substrate;

an electrical component mounted on the substrate, the substrate and the electrical component defining a surface contour; and

a covering film having at least one part connected to the electrical component and to the substrate such that the surface contour defined by the electrical component and the substrate is mapped in a surface contour of the covering film,

wherein the covering film is formed of a composite material comprising a plastic material and at least one filler material that is different from the plastic material.

15. (NEW) The electrical device according to claim 14, wherein the composite material has a coefficient of thermal expansion that substantially matches a coefficient of thermal expansion of the electrical component.

16. (New) The electrical device according to claim 15, wherein the coefficient of thermal expansion of the composite material is in a range from 7 ppm/K to 50 ppm/K.

17. (New) The electrical device according to one of claims 14, wherein the filler material is thermally and/or electrically conductive.

18. (New) The electrical device according to one of claims 14, wherein the filler material is in a powder and/or fiber form.

19. (New) The electrical device according to claim 14, wherein the electrical device has an additional film formed on at least part of the electrical component and at least part of the substrate such that the surface contour of the electrical component and the substrate is mapped in a surface contour of the additional film .

20. (New) The electrical device according claim 19, wherein the additional film is formed of a composite material comprising a filler material that is different from the filler material of the covering film.

21. (New) The electrical device according to one of claims 14, wherein the electrical component is a semiconductor component.

22. (New) The electrical device according to claim 21, wherein the semiconductor component is a power semiconductor component selected from the group consisting of MOSFET components, IGBT components and bipolar transistor components.

23. (New) The electrical device according to one of claims 16, wherein the filler material is thermally and/or electrically conductive.

24. (New) The electrical device according to one of claims 23, wherein the filler material is in a powder and/or fiber form.

25. (New) The electrical device according to claim 24, wherein the electrical device has an additional film formed on at least part of the electrical component and at least part of the substrate such that the surface contour of the electrical component and the substrate is mapped in a surface contour of the additional film.

26. (New) The electrical device according claim 25, wherein the additional film is formed of a composite material comprising a filler material that is different from the filler material of the covering film.

27. (New) The electrical device according to claim 26, wherein the semiconductor component is a power semiconductor component selected from the group consisting of MOSFET components, IGBT components and bipolar transistor components.

28. (New) A method for producing an electrical device, comprising:
forming an electrical component on a substrate such that the substrate and the electrical component define a surface contour; and
laminating a covering film onto at least part of the electrical component and at least part of the substrate, such that the surface contour defined by the electrical component and the substrate is mapped in a surface contour of the covering film, the covering film being formed of a composite material comprising a plastic material and at least one filler material that is different from the plastic material.

29. (New) The method according to claim 23, wherein the covering film is laminated using a vacuum-lamination technique.

30. (New) The method according to claim 23, wherein a tempering step is performed during and/or after laminating the covering film.

31. (New) The method according to claim 23, wherein the plastic material used to form the covering film is at least one plastic material selected from the group consisting of a polyimide, a polyethylene, a polyphenol, a polyetheretherketone and an epoxy resin.

32. (new) The method according to claim 26, wherein
the electrical device has an additional film formed on at least part of the electrical component and at least part of the substrate such that the surface contour of the electrical component and the substrate is mapped in a surface contour of the additional film, and
the additional film is formed composite material comprising a plastic material and a filler material that is different from the filler material of the covering film, and
the plastic material used to form the additional film is at least one plastic material selected from the group consisting of a polyimide, a polyethylene, a polyphenol, a polyetheretherketone and an epoxy resin.

33. (New) The method according to claim 29, wherein a tempering step is performed during and/or after laminating the covering film.